



Material Content Data Sheet



Sales Product Name		IPC100N04S5-2R8		Issued		1. August 2018		
MA#		MA001496362						
Package		PG-TDSON-8-33		Weight*		111.56 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.595	0.53	0.53	5334	5334
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		143	
	non noble metal	iron	7439-89-6	0.053	0.05		477	
	non noble metal	copper	7440-50-8	53.151	47.65	47.71	476425	477045
	noble metal	gold	7440-57-5	0.046	0.04	0.04	409	409
encapsulation	organic material	carbon black	1333-86-4	0.076	0.07		685	
	plastics	epoxy resin	-	6.036	5.41		54105	
	inorganic material	silicondioxide	60676-86-0	32.090	28.76	34.24	287645	342435
leadfinish	non noble metal	tin	7440-31-5	1.574	1.41	1.41	14107	14107
plating	noble metal	silver	7440-22-4	0.209	0.19	0.19	1875	1875
solder	non noble metal	tin	7440-31-5	0.017	0.02		155	
	noble metal	silver	7440-22-4	0.022	0.02		194	
	non noble metal	lead	7439-92-1	0.827	0.74	0.78	7415	7764
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.005	0.00		45	
	non noble metal	iron	7439-89-6	0.017	0.02		151	
	non noble metal	copper	7440-50-8	16.828	15.08	15.10	150835	151031
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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